

# **Dual N-Channel Enhancement Mode MOSFET**

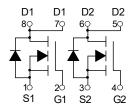
## **Description**

The UPA2751GR-E1-AT uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

# D1 D1 D2 D2 SOP-8

### **General Features**

V<sub>DS</sub> = 30V I<sub>D</sub> = 10A  $R_{DS(ON)}$  < 12m $\Omega$  @  $V_{GS}$ =10 V  $R_{DS(ON)}$  < 18m $\Omega$  @ V<sub>GS</sub>=4.5V



# **Application**

Battery protection Load switch Uninterruptible power supply

**Dual N-Channel MOSFET** 

# **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
UPA2751GR-E1-AT	SOP-8	HXY MOSFET	3000

# Absolute Maximum Ratings@T<sub>i</sub>=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	30	V
V <sub>GS</sub>	Gate-Source Voltage	<u>+</u> 20	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Drain Current, V <sub>GS</sub> @ 4.5V <sup>3</sup>	10	А
I <sub>D</sub> @T <sub>A</sub> =70°C	Drain Current, V <sub>GS</sub> @ 4.5V <sup>3</sup>	8	А
Ірм	Pulsed Drain Current <sup>1</sup>	55	А
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation	2	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Rthj-a	Maximum Thermal Resistance, Junction- ambient <sup>3</sup>	62.5	°C/W

# Dual N-Channel Enhancement Mode MOSFET

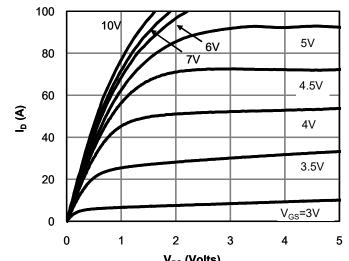
# **Electrical Characteristics Ta = 25°C**

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Drain-Source Breakdown Voltage	VDSS	ID=250 μ A, VGS=0V	30			V	
Zoro Coto Voltago Drain Current	Ipss	VDS=30V, VGS=0V			1	uA	
Zero Gate Voltage Drain Current	1088	VDS=30V, VGS=0V, TJ=55℃			5		
Gate-Body Leakage Current	Igss	VDS=0V, VGS=±20V			±100	nA	
Gate Threshold Voltage	VGS(th)	VDS=VGS, ID=250uA	1.5		2.5	V	
	RDS(On)	Vgs=10V, ID=10A			12		
Static Drain-Source On-Resistance		Vgs=10V, Id=10A TJ=125°C			18	$\mathbf{m}$ Ω	
		Vgs=4.5 V, ID=8A			16.5	1	
On State Drain Current	ID(ON)	Vgs=10V, Vds=5V	55			Α	
Forward Transconductance	gFS	VDS=5V, ID=10A		43		S	
Input Capacitance	Ciss		610		910	pF	
Output Capacitance	Coss	Vgs=0V, Vps=15V, f=1MHz	88		160		
Reverse Transfer Capacitance	Crss		40		100		
Gate Resistance	Rg	Vgs=0V, Vps=0V, f=1MHz	8.0		2.4	Ω	
Total Gate Charge (10V)	Qg		11		17	nC	
Total Gate Charge (4.5V)	Qg	Vgs=10V, Vps=15V, lp=10A	5		8		
Gate Source Charge	Qgs	VGS-10V, VDS-13V, ID-10A		2.4			
Gate Drain Charge	Qgd			3			
Turn-On DelayTime	td(on)			4.4			
Turn-On Rise Time	tr	Vgs=10V, Vds=15V, RL=1.5Ω,		9		ns	
Turn-Off DelayTime	t <sub>d(off)</sub>	Rgen=3Ω		17			
Turn-Off Fall Time	tf			6			
Body Diode Reverse Recovery Time	trr	IF= 10A, dı/dt= 500A/us	5.6		8		
Body Diode Reverse Recovery Charge	Qrr	7 IF- 10A, UI/UI- 300A/US	6.4		9.6	nC	
Maximum Body-Diode Continuous Current	Is				2.5	Α	
Diode Forward Voltage	Vsd	Is=1A,Vgs=0V			1	V	

Note. The static characteristics in Figures 1 to 6 are obtained using <300us pulses, duty cycle 0.5% max.



# **Typical Characterisitics**



 $\label{eq:VDS} V_{DS} \, \mbox{(Volts)}$  Fig 1: On-Region Characteristics (Note E)

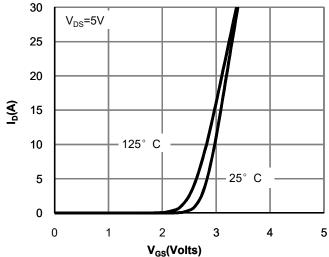
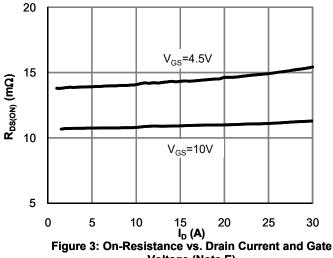


Figure 2: Transfer Characteristics (Note E)



Voltage (Note E)

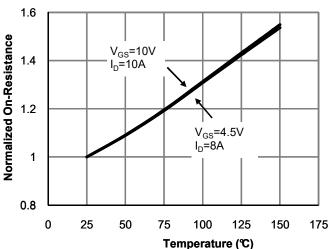
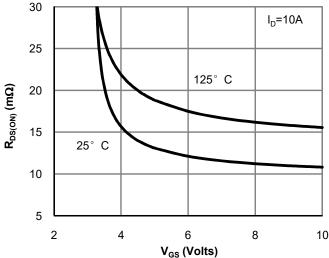
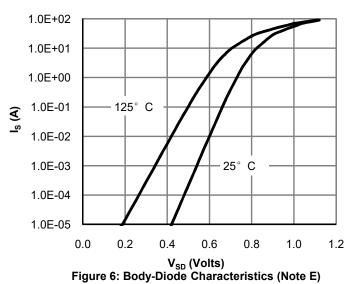


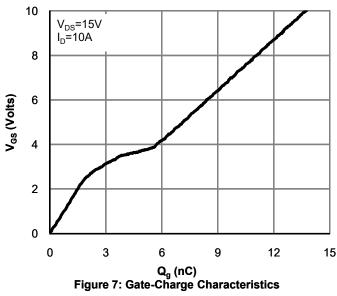
Figure 4: On-Resistance vs. Junction Temperature (Note E)



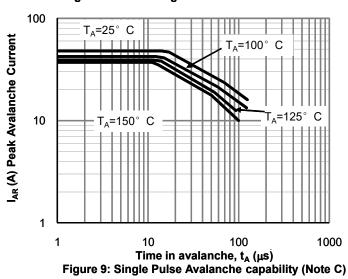
 $V_{GS}$  (Volts) Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)







1200 1000  $C_{iss}$ Capacitance (pF) 800 600 400 Coss 200 0 5 10 15 20 25 0 30 V<sub>DS</sub> (Volts)
Figure 8: Capacitance Characteristics



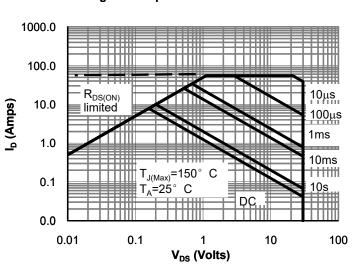


Figure 10: Maximum Forward Biased Safe Operating Area (Note F)

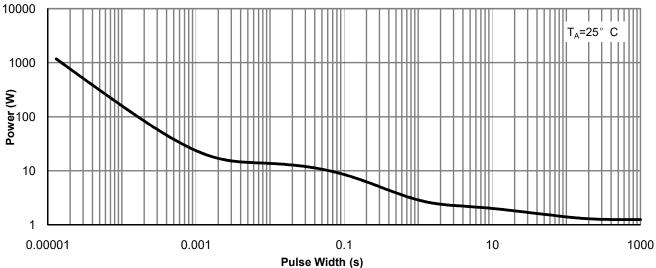
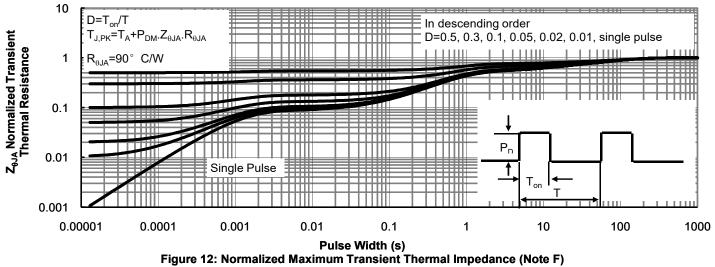
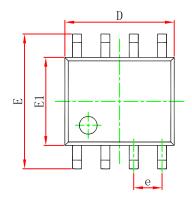


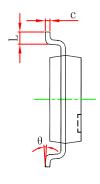
Figure 11: Single Pulse Power Rating Junction-to-Ambient (Note F)

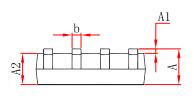




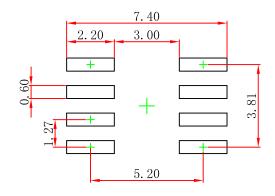
# **SOP-8 Package Outline Dimensions**







Symbol	Dimensions In Millimeters		Dimensions In Inches			
	Min	Max	Min	Max		
A	1.350	1.750	0.053	0.069		
A1	0.100	0. 250	0.004	0.010		
A2	1.350	1.550	0.053	0.061		
b	0.330	0.510	0.013	0. 020		
c	0.170	0. 250	0.007	0.010		
D	4.800	5.000	0. 189	0. 197		
e	1. 270 (	1.270 (BSC)		0.050 (BSC)		
E	5.800	6. 200	0. 228	0. 244		
E1	3.800	4.000	0. 150	0. 157		
L	0.400	1. 270	0.016	0.050		
θ	0°	8°	0°	8°		



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
  3.The pad layout is for reference purposes only.



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